

Information Letter Number: 224201**Date:** 22-Nov-2022**Title:** New Wirebonder for SHT3xA**Product Identification:** All products of the SHT3xA family**Reason for Change:** Design Production Logistics Manufacturing Location Quality/Reliability Upgrade**Change Description:**

New wirebonders, new plasma machine and new mold machine must be installed for capacity increase and risk mitigation. Therefore, SHT3xA will be produced on new wire bonder equipment, new plasma machine and new mold machine. Consequently, new processes for cleaning, wire bonding and transfer molding will be developed on new equipment. There is no material change (wire bond material; mold compound). Moreover, form, fit and function of final sensors are not affected by this continuous improvement process (CIP).

Identification Method to Distinguish Change:**Samples:** available will be available in not applicable**Quantifiable Impact on Quality & Reliability:** No impact**Estimated Implementation Date*:** 1st of May 2023

** The Estimated Implementation Date is the forecasted date that a customer may expect to receive changed product. This may be affected by fluctuations in supply and demand.*

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If you have questions about this Information Letter, please send them to the Sensirion contact e-mail address listed above.

Manufacturer part number**SHT30A-DIS-B2.5kS****SHT30A-DIS-B10kS****SHT31A-DIS-B2.5kS****SHT31A-DIS-B10kS****SHT35A-DIS-B2.5kS****SHT35A-DIS-B10kS**